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November 21, 2001

Box PATENT APPLICATION

Commissioner for Patents
Washington, D.C. 20231

Re: New U.S. Patent Appl.
Our Ref: 381NP/50670

Sir:

Transmitted herewith for filing is the patent application of:

Hiroyuki KADOTA

entitled: **ELECTROLYTIC GOLD PLATING METHOD AND APPARATUS
THEREFOR**

Enclosed are:

1. Specification, including 16 claims (pages 25, plus specification front page).
2. 4 Sheets of X Formal Informal drawings showing Figs. 1-5.
3. X Declaration and Power of Attorney (**executed**).
4. Assignment of the invention to Hitachi Kyowa Engineering Co., Ltd.
5. The filing fee has been calculated as shown below:

Basic Fee						\$370/740	=	\$740.00
Total Claims	<u>30</u>	-	<u>20</u>	=	<u>10</u>	x	\$9/18	= \$180.00
Independent Claims	<u>9</u>	-	<u>3</u>	=	<u>6</u>	x	\$42/84	= \$504.00
Multiple Dependent Claim Presented							\$140/280	= \$280.00
Total Filing Fee								<u>\$1,704.00</u>

Two checks in the amount of \$ 1,704.00 for the filing fee and \$ 40.00 for the assignment recording fee are enclosed. The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to Deposit Account No. 05-1323 (Docket #381NP/50670). A duplicate copy of this sheet is enclosed.

Respectfully submitted,



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JFM:WAZ:vca



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PATENT TRADEMARK OFFICE

